

TIL111M, TIL117M, MOC8100M

General Purpose 6-Pin Phototransistor Optocouplers

Features

- UL recognized (File # E90700)
- VDE recognized (File #102497 for white package)
 - Add option V (e.g., TIL111VM)

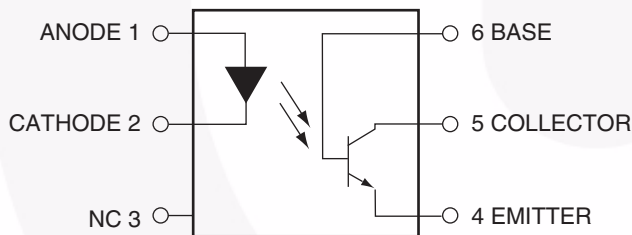
Applications

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs
- Appliance sensor systems
- Industrial controls

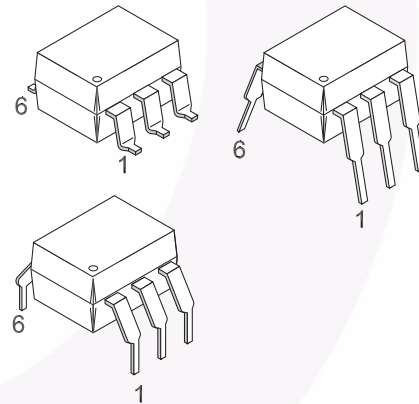
General Description

The MOC8100M, TIL111M and TIL117M optocouplers consist of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 6-pin dual in-line package.

Schematic



Package Outlines



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Device	Value	Units
TOTAL DEVICE				
T _{STG}	Storage Temperature	All	-40 to +150	°C
T _{OPR}	Operating Temperature	All	-40 to +100	°C
T _{SOL}	Lead Solder Temperature	All	260 for 10 sec	°C
P _D	Total Device Power Dissipation @ T _A = 25°C Derate above 25°C	All	250	mW
			2.94	mW/°C
EMITTER				
I _F	DC/Average Forward Input Current	All	60	mA
V _R	Reverse Input Voltage	TIL111M	3	V
		MOC8100M, TIL117M	6	
I _{F(pk)}	Forward Current – Peak (300µs, 2% Duty Cycle)	All	3	A
P _D	LED Power Dissipation @ T _A = 25 °C Derate above 25°C	All	120	mW
			1.41	mW/°C
DETECTOR				
V _{CEO}	Collector-Emitter Voltage	All	30	V
V _{CBO}	Collector-Base Voltage	All	70	V
V _{ECO}	Emitter-Collector Voltage	TIL111M, TIL117M	7	V
V _{EBO}	Emitter-Base Voltage	All	7	
P _D	Detector Power Dissipation @ T _A = 25 °C Derate above 25°C	All	150	mW
			1.76	mW/°C

Electrical Characteristics (T_A = 25°C unless otherwise specified.)

Individual Component Characteristics

Symbol	Parameter	Test Conditions		Device	Min.	Typ.*	Max.	Unit
EMITTER								
V _F	Input Forward Voltage	I _F = 16mA	T _A = 25°C	TIL111M		1.2	1.4	V
		I _F = 10mA for MOC8100M, I _F = 16mA; for TIL117M	T _A = 0°C–70°C	MOC8100M, TIL117M		1.2	1.4	
			T _A = -55°C			1.32		
			T _A = +100°C			1.10		
I _R	Reverse Leakage Current	V _R = 3.0V		TIL111M, TIL117M		0.001	10	μA
		V _R = 6.0V		MOC8100M		0.001	10	μA
DETECTOR								
BV _{CEO}	Collector-Emitter Breakdown Voltage	I _C = 1.0mA, I _F = 0		All	30	100		V
BV _{CBO}	Collector-Base Breakdown Voltage	I _C = 10μA, I _F = 0		All	70	120		V
BV _{EBO}	Emitter-Base Breakdown Voltage	I _E = 10μA, I _F = 0		All	7	10		V
BV _{ECO}	Emitter-Collector Breakdown Voltage	I _F = 100μA, I _F = 0		TIL111M, TIL117M	7	10		V
I _{CEO}	Collector-Emitter Dark Current	V _{CE} = 10V, I _F = 0		TIL111M, TIL117M		1	50	nA
		V _{CE} = 5V, T _A = 25°C		MOC8100M		0.5	25	nA
		V _{CE} = 30V, I _F = 0, T _A = 70°C		TIL117M, MOC8100M		0.2	50	μA
I _{CBO}	Collector-Base Dark Current	V _{CB} = 10V		TIL111M, TIL117M			20	nA
		V _{CB} = 5V		MOC8100M			10	nA
C _{CE}	Capacitance	V _{CE} = 0V, f = 1MHz		All		8		pF

*All Typical values at T_A = 25°C

Electrical Characteristics (Continued) ($T_A = 25^\circ\text{C}$ unless otherwise specified.)

Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min	Typ*	Max	Unit
DC CHARACTERISTICS							
CTR _{CE}	Current Transfer Ratio, Collector to Emitter	I _F = 10mA, V _{CE} = 10V	TIL117M	50			%
		I _F = 1mA, V _{CE} = 5V	MOC8100M	50			%
		I _F = 1mA, V _{CE} = 5V, T _A = 0°C to +70°C		30			
I _{C(ON)}	On-State Collector Current (Phototransistor Operation)	I _F = 16mA, V _{CE} = 0.4V	TIL111M	2			mA
	On-State Collector Current (Photodiode Operation)	I _F = 16mA, V _{CB} = 0.4V		7			μA
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	I _C = 500μA, I _F = 10mA	TIL117M			0.4	V
		I _C = 2mA, I _F = 16mA	TIL111M			0.4	
		I _C = 100μA, I _F = 1mA	MOC8100M			0.5	
AC CHARACTERISTICS							
T _{ON}	Turn-On Time	I _C = 2mA, V _{CC} = 10V, R _L = 100Ω (Fig. 11)	MOC8100M			20	μs
			TIL117M			10	
T _{OFF}	Turn-Off Time		MOC8100M			20	μs
			TIL117M			10	
t _r	Rise Time		MOC8100M		2		μs
t _f	Fall Time		TIL117M		2		
t _r	Rise Time (Phototransistor Operation)	I _{C(ON)} = 2mA, V _{CC} = 10V, R _L = 100Ω (Fig. 11)	TIL111M			10	μs
t _f	Fall Time (Phototransistor Operation)						

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	f = 60Hz, t = 1 sec.	7500			V _{AC(rms)}
R _{ISO}	Isolation Resistance	V _{I-O} = 500 VDC	10 ¹¹			Ω
C _{ISO}	Isolation Capacitance	V _{I-O} = 0, f = 1MHz		0.2		pF

*All Typical values at T_A = 25°C

Typical Performance Characteristics

Fig. 1 LED Forward Voltage vs. Forward Current

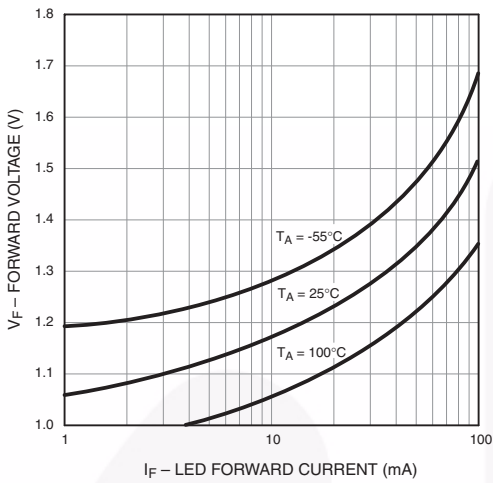


Fig. 2 Normalized CTR vs. Forward Current

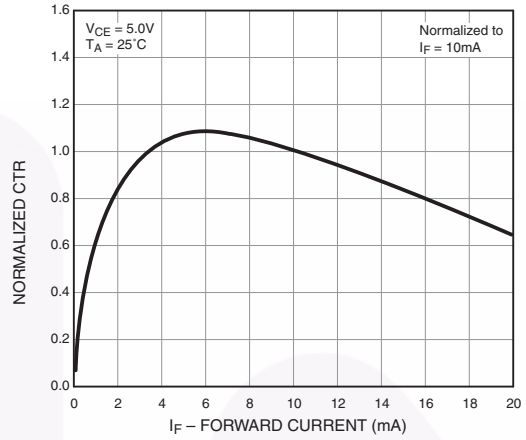


Fig. 3 Normalized CTR vs. Ambient Temperature

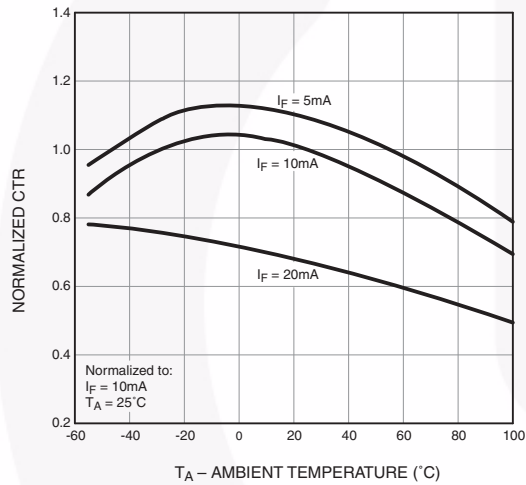


Fig. 4 CTR vs. RBE (Unsaturated)

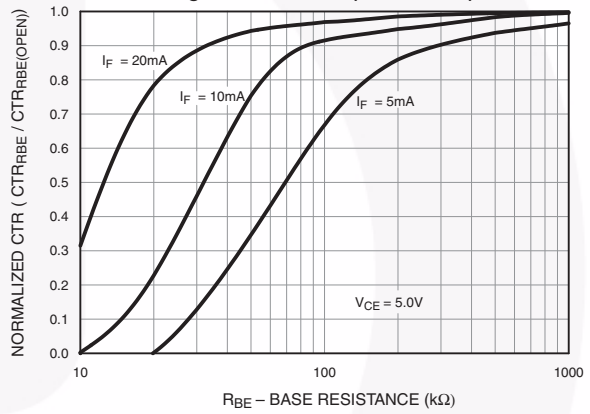


Fig. 5 CTR vs. RBE (Saturated)

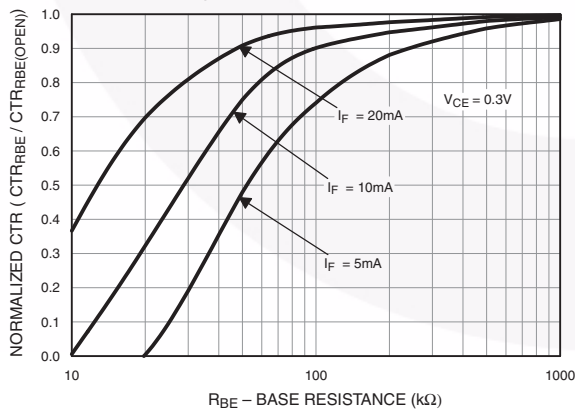
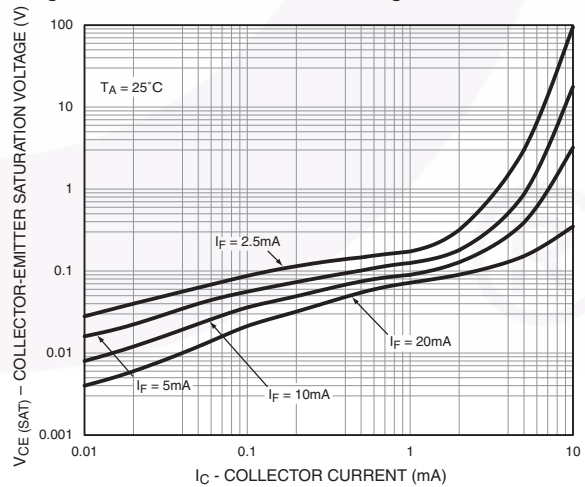


Fig. 6 Collector-Emitter Saturation Voltage vs. Collector Current



Typical Performance Characteristics (Continued)

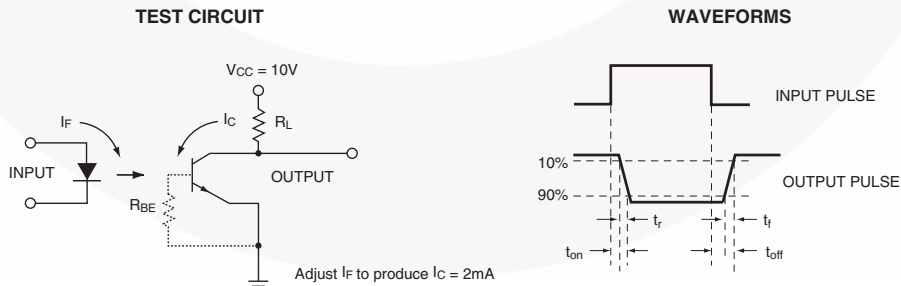
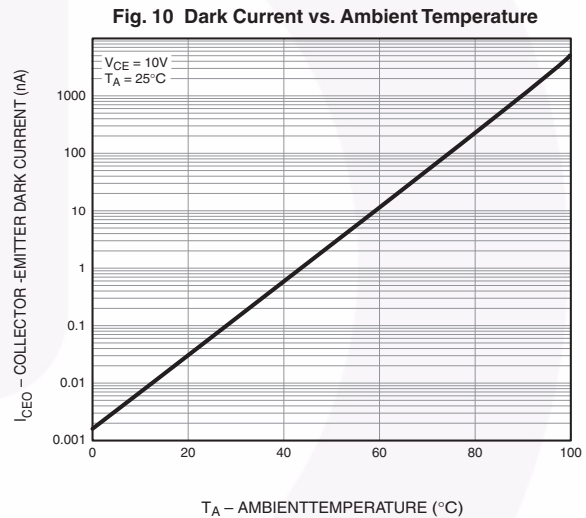
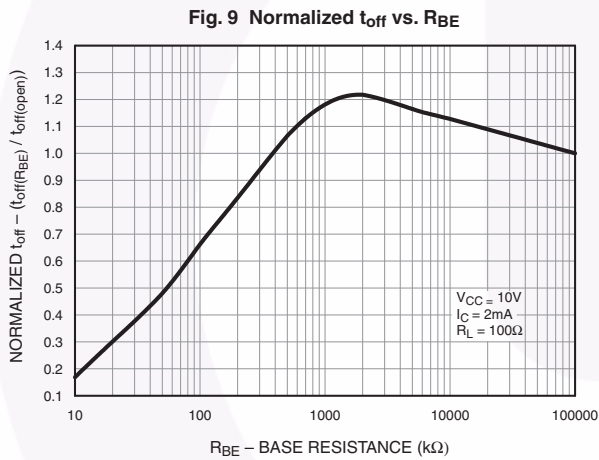
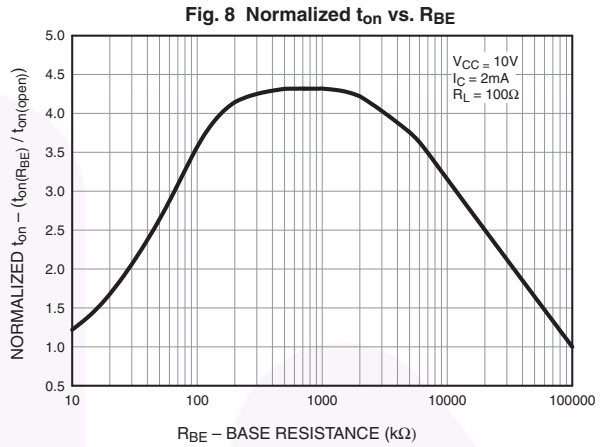
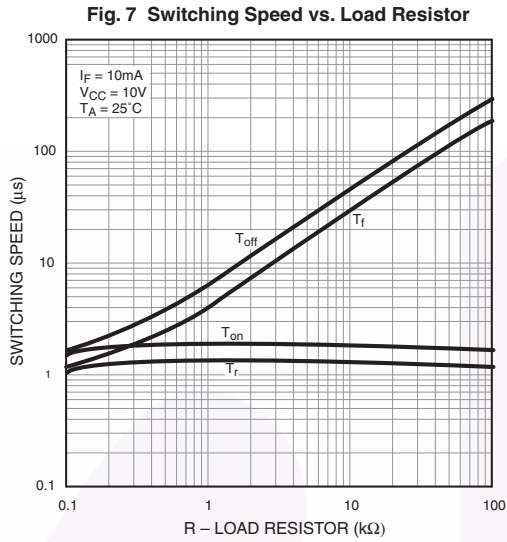
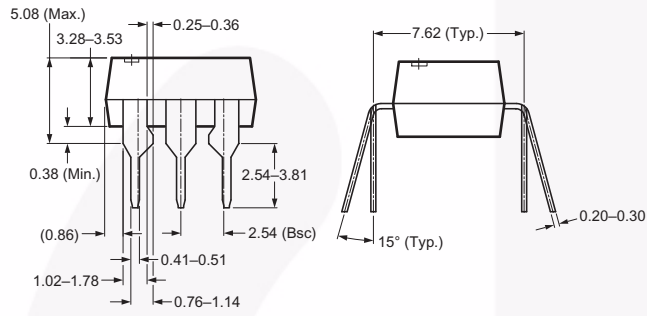
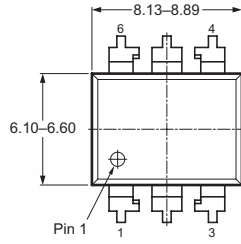


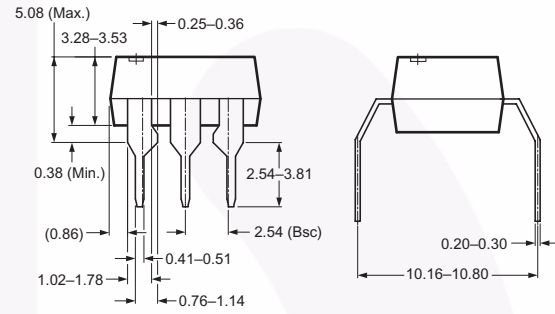
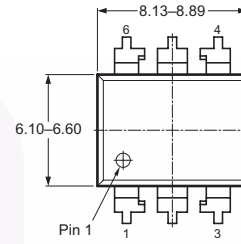
Figure 11. Switching Time Test Circuit and Waveforms

Package Dimensions

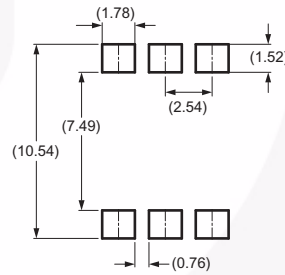
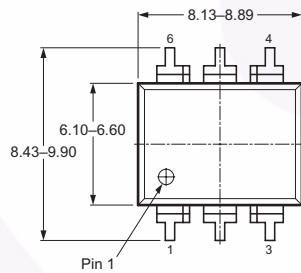
Through Hole



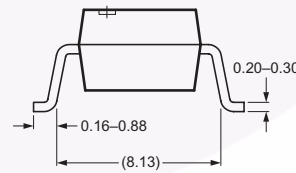
0.4" Lead Spacing



Surface Mount



Recommended Pad Layout

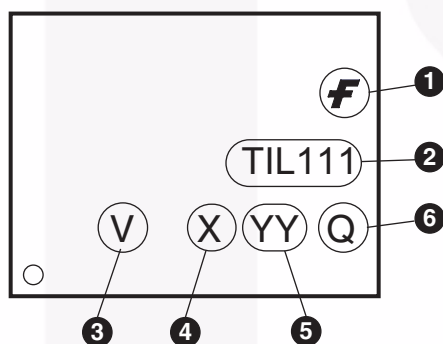


Note:
All dimensions in mm.

Ordering Information

Option	Order Entry Identifier (Example)	Description
No option	TIL111M	Standard Through Hole Device
S	TIL111SM	Surface Mount Lead Bend
SR2	TIL111SR2M	Surface Mount; Tape and Reel
T	TIL111TM	0.4" Lead Spacing
V	TIL111VM	VDE 0884
TV	TIL111TVM	VDE 0884, 0.4" Lead Spacing
SV	TIL111SVM	VDE 0884, Surface Mount
SR2V	TIL111SR2VM	VDE 0884, Surface Mount, Tape and Reel

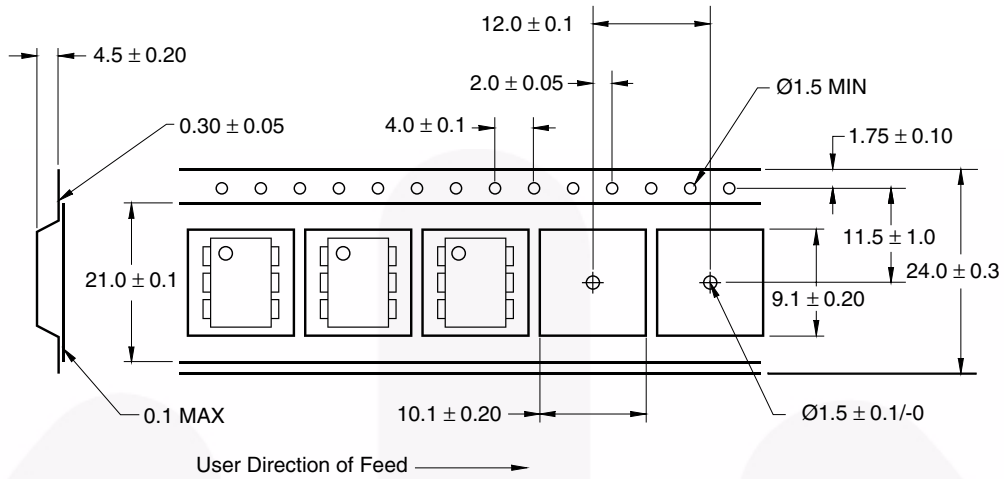
Marking Information



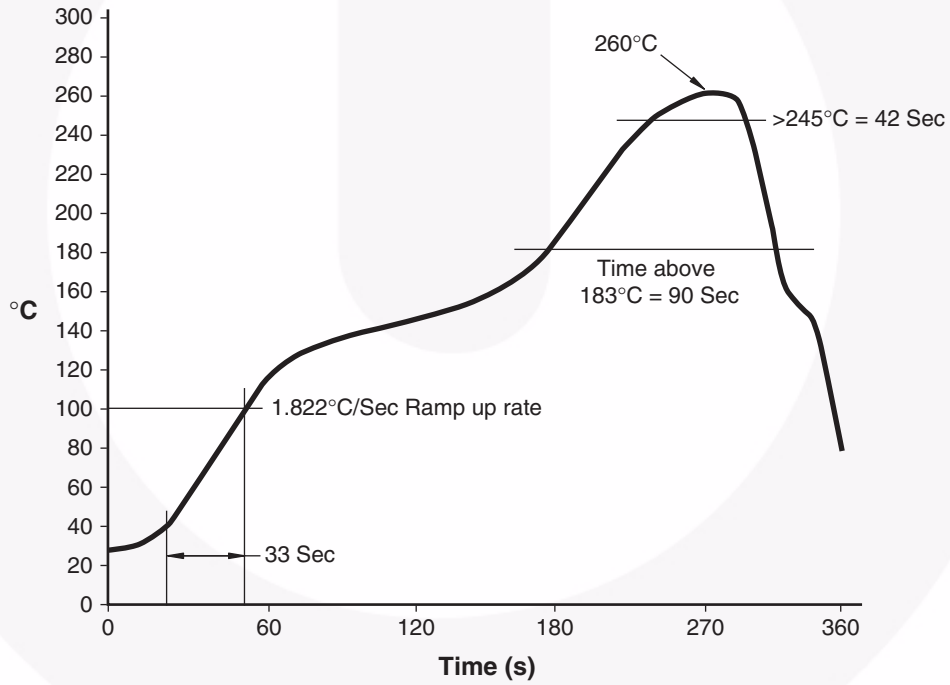
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '7'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

*Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

Carrier Tape Specification









Reflow Profile





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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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Rev. 138